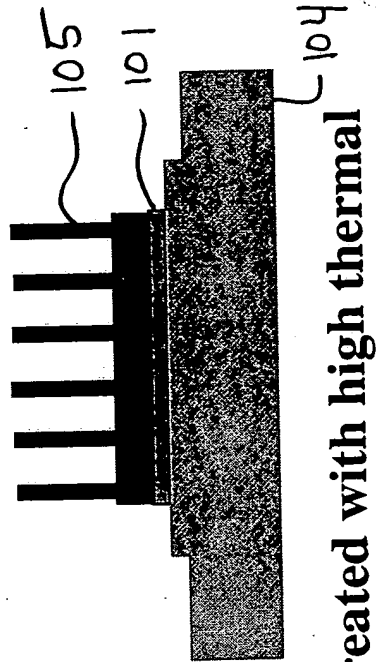


100 ↙

Figure 1B
Heat Sink



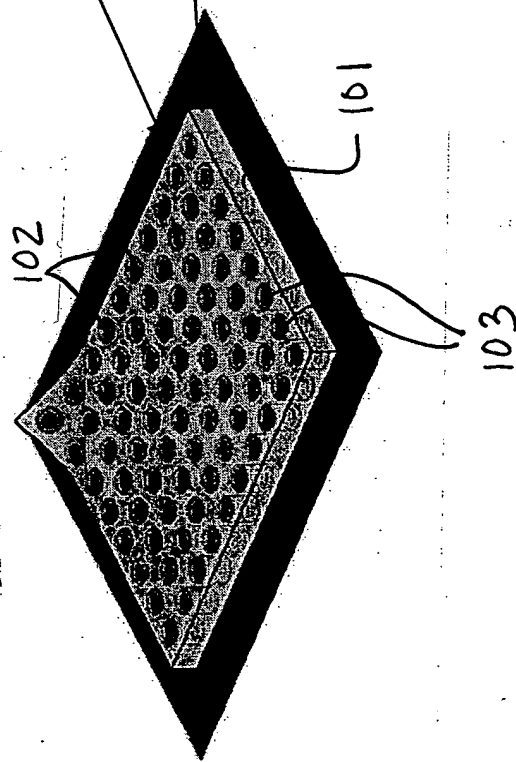
Thermal
membrane
film

Device to
be cooled.

Hole treated with high thermal
conductor

PDMS Membrane

FIGURE 1A

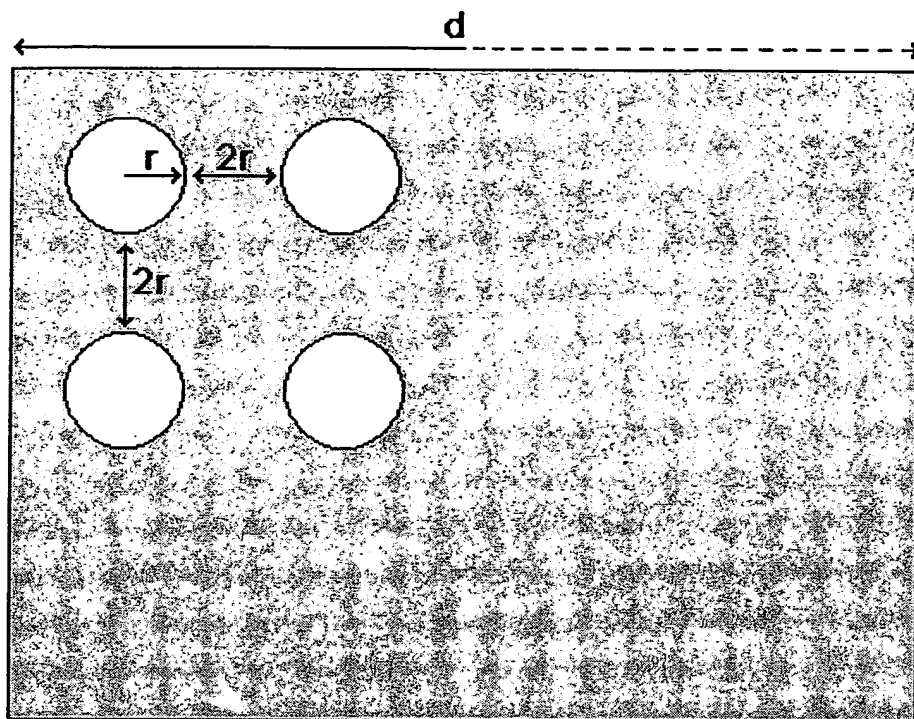


102

101

103

FIGURE 2A



200



FIGURE 2B

300 ↓

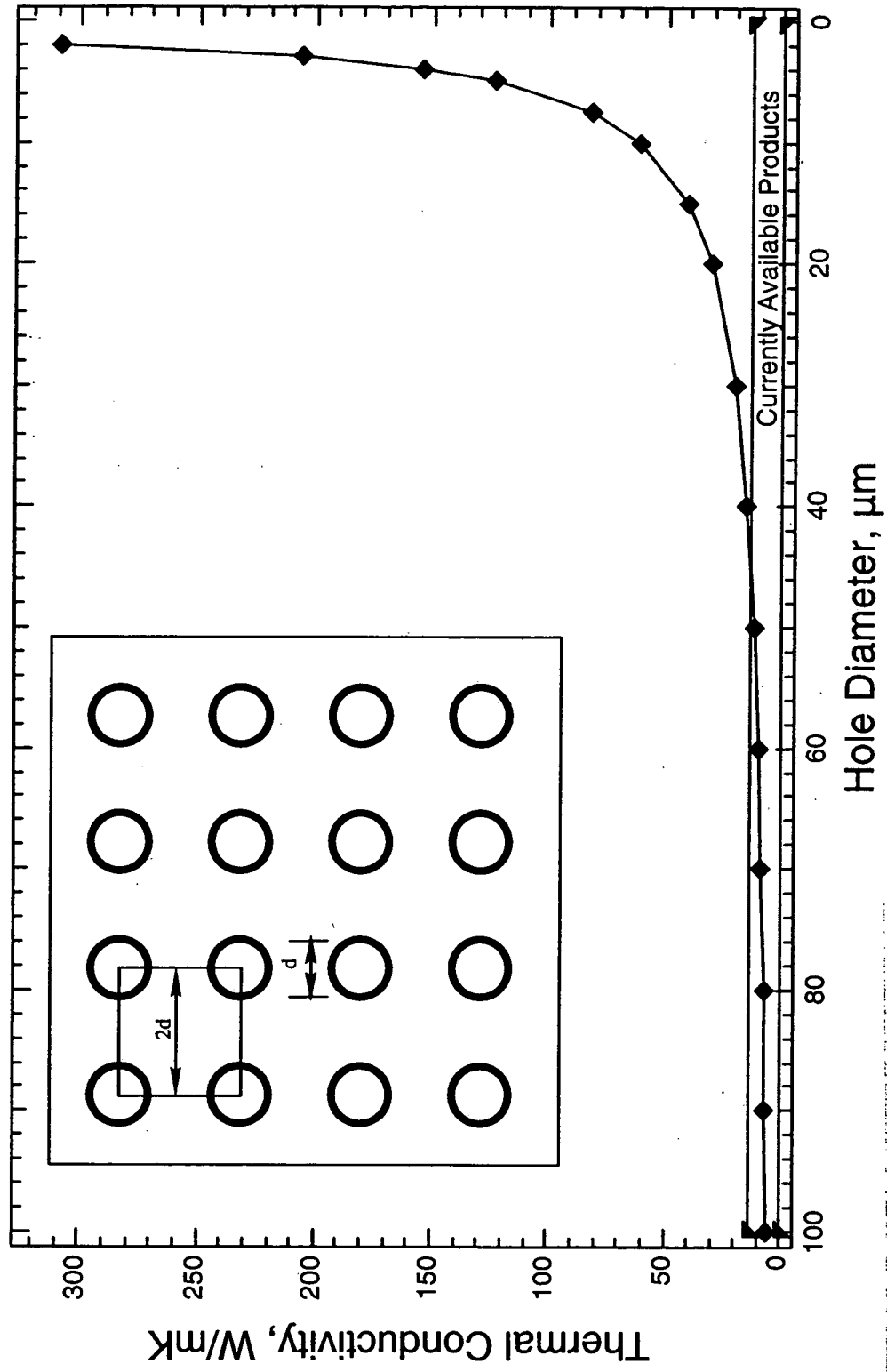
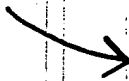


FIGURE 3

350



Pentium IVR Heat Sinks

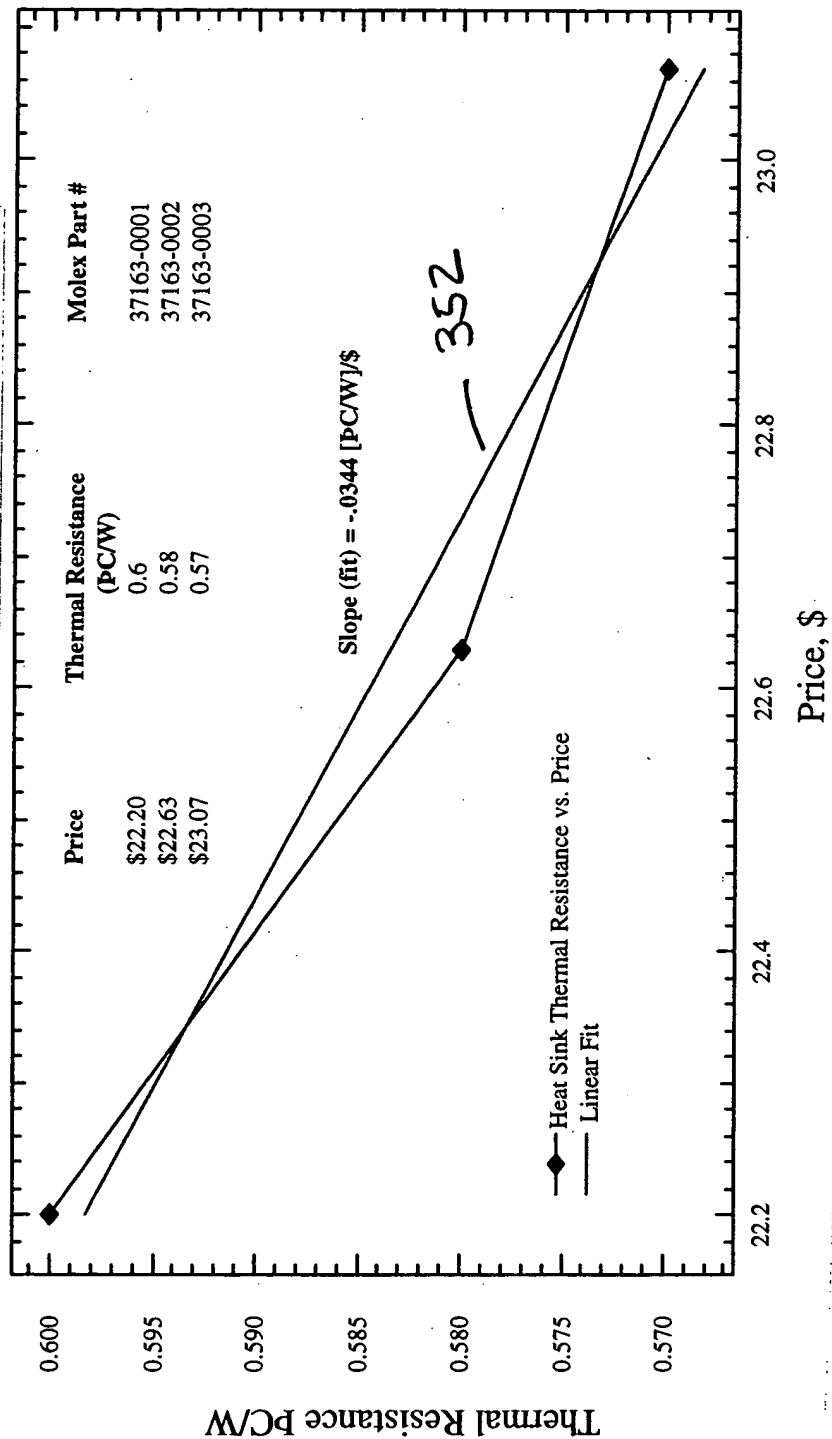


FIGURE 4

400 ↘

Hard Bake Cure Station

